



景碩科技股份有限公司
Kinsus Interconnect Technology Corp.

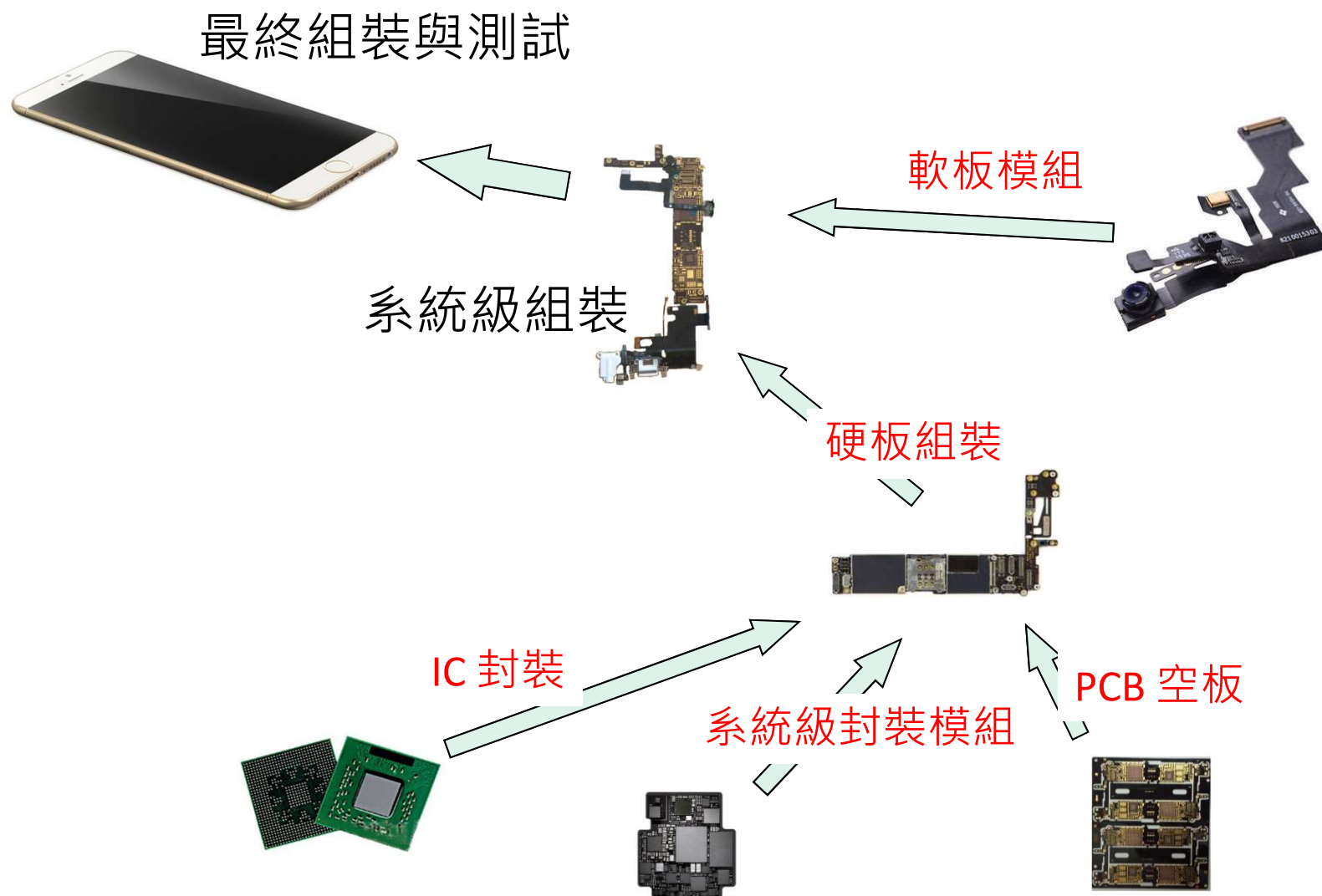
Mar 2024



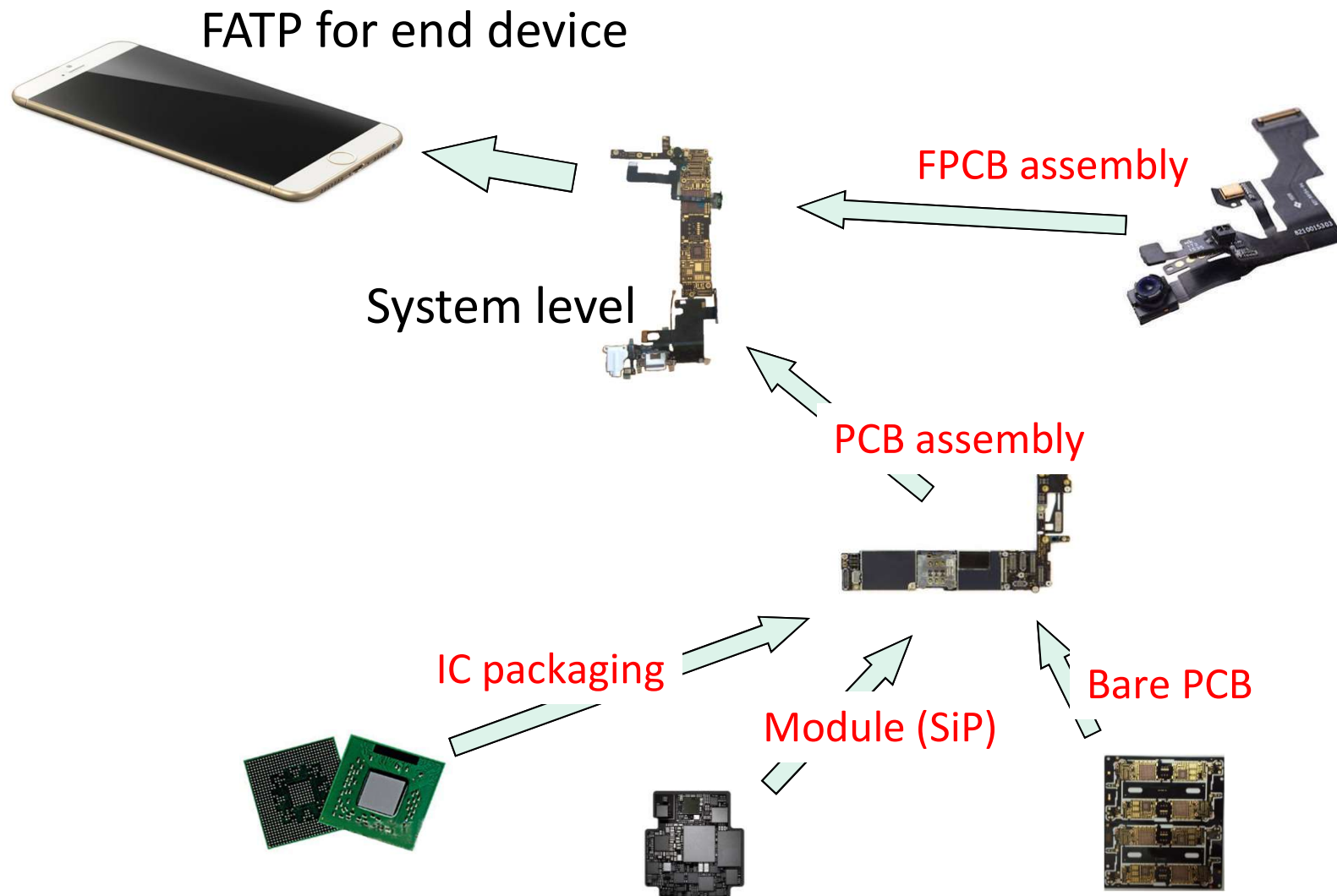
IC 封裝技術

IC Packaging Technology

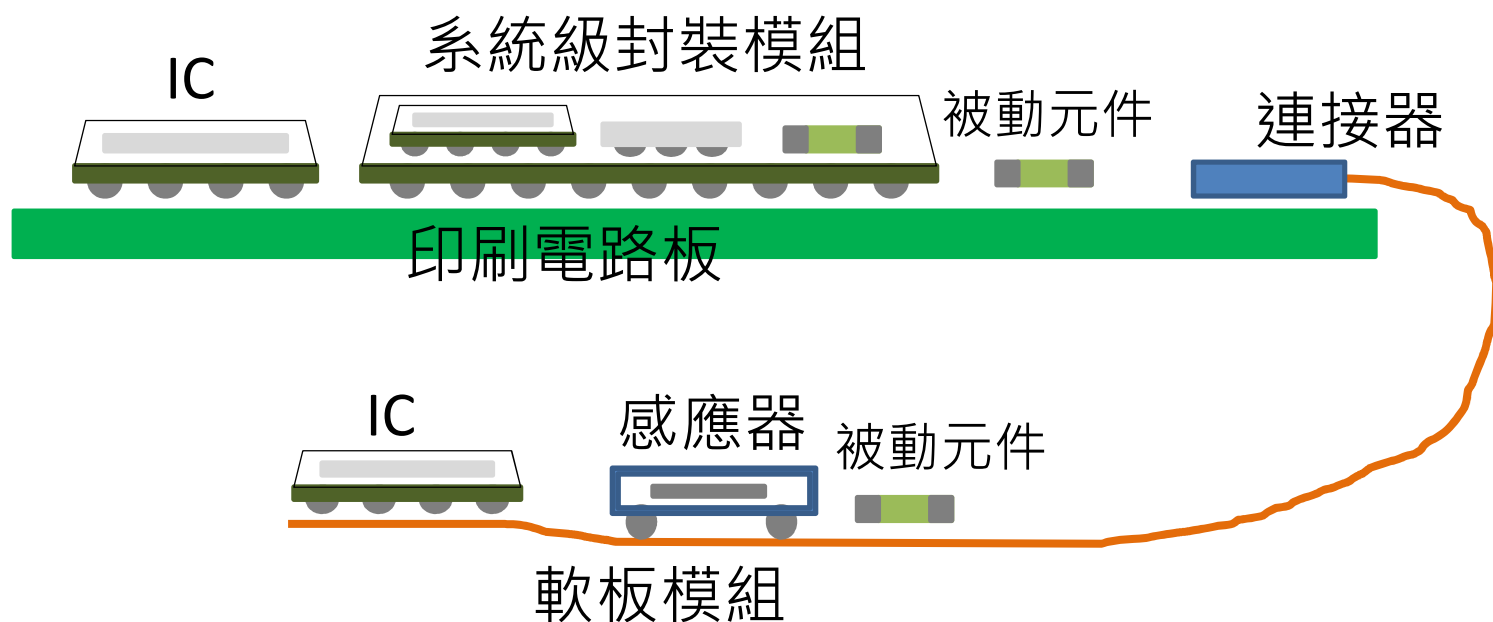
電子產品構裝的各個層次



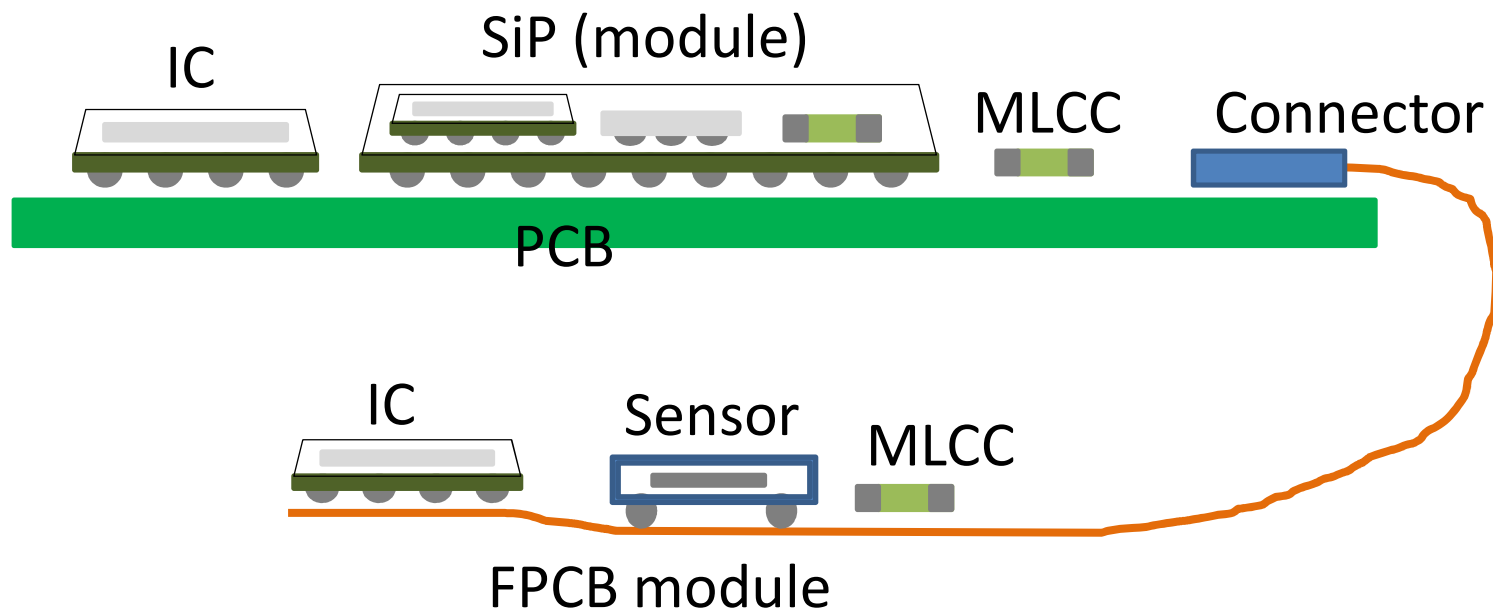
Levels of Assembly



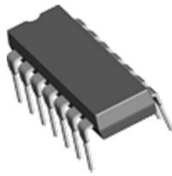
電子產品的組裝結構



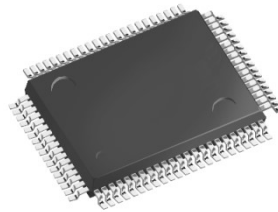
Basic structure of electronic devices



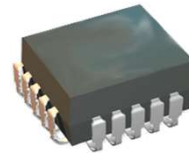
各種形式的IC 封裝



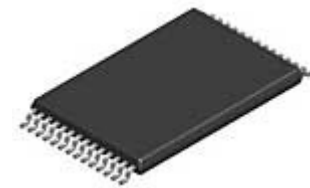
DIP



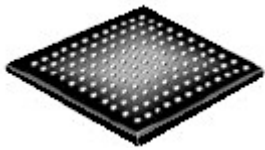
QFP



PLCC



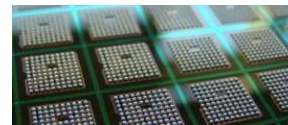
TSOP



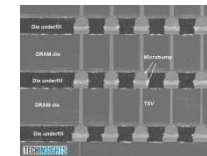
PBGA/
Flip-Chip BGA



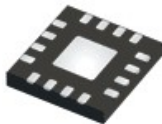
CSP



WLP



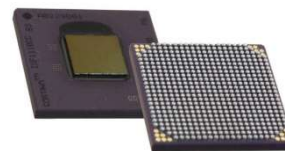
TSV



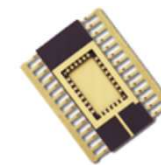
QFN



DFN



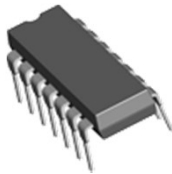
Ceramic BGA



Ceramic chip

BGA 封裝 市場規模: 2023 年828 億顆, 產值 161億美元

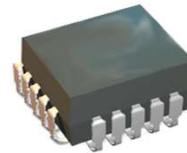
Different types of IC packaging



DIP



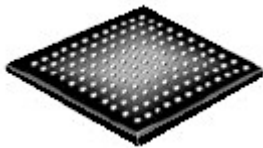
QFP



PLCC



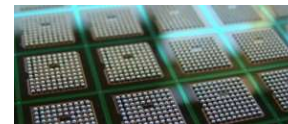
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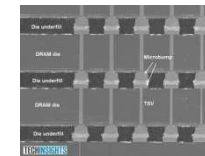
PBGA/
Flip-Chip BGA



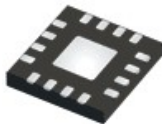
CSP



WLP



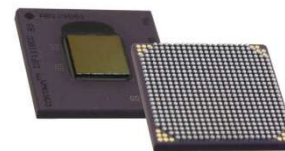
TSV



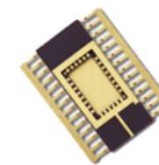
QFN



DFN

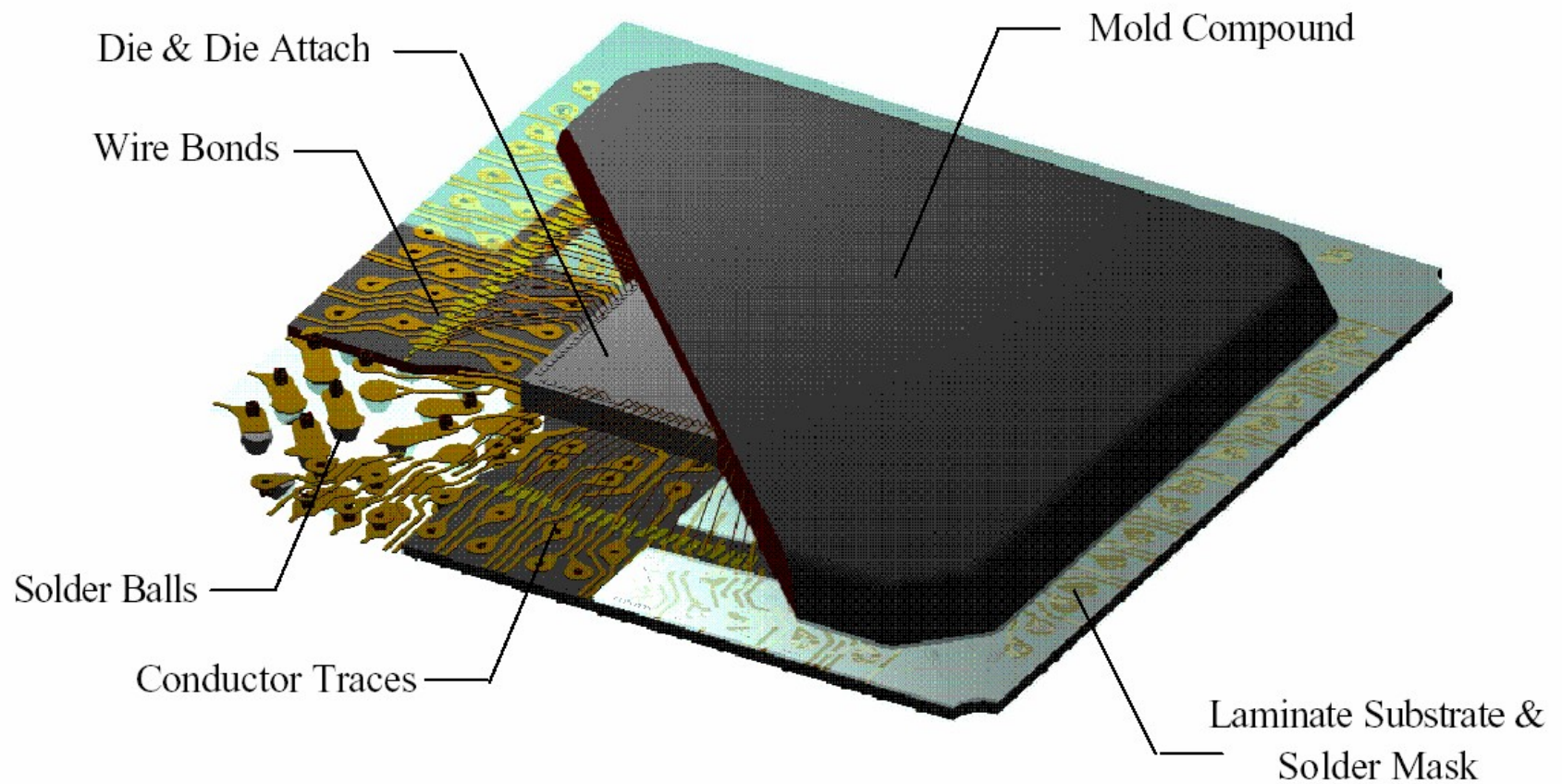


Ceramic BGA

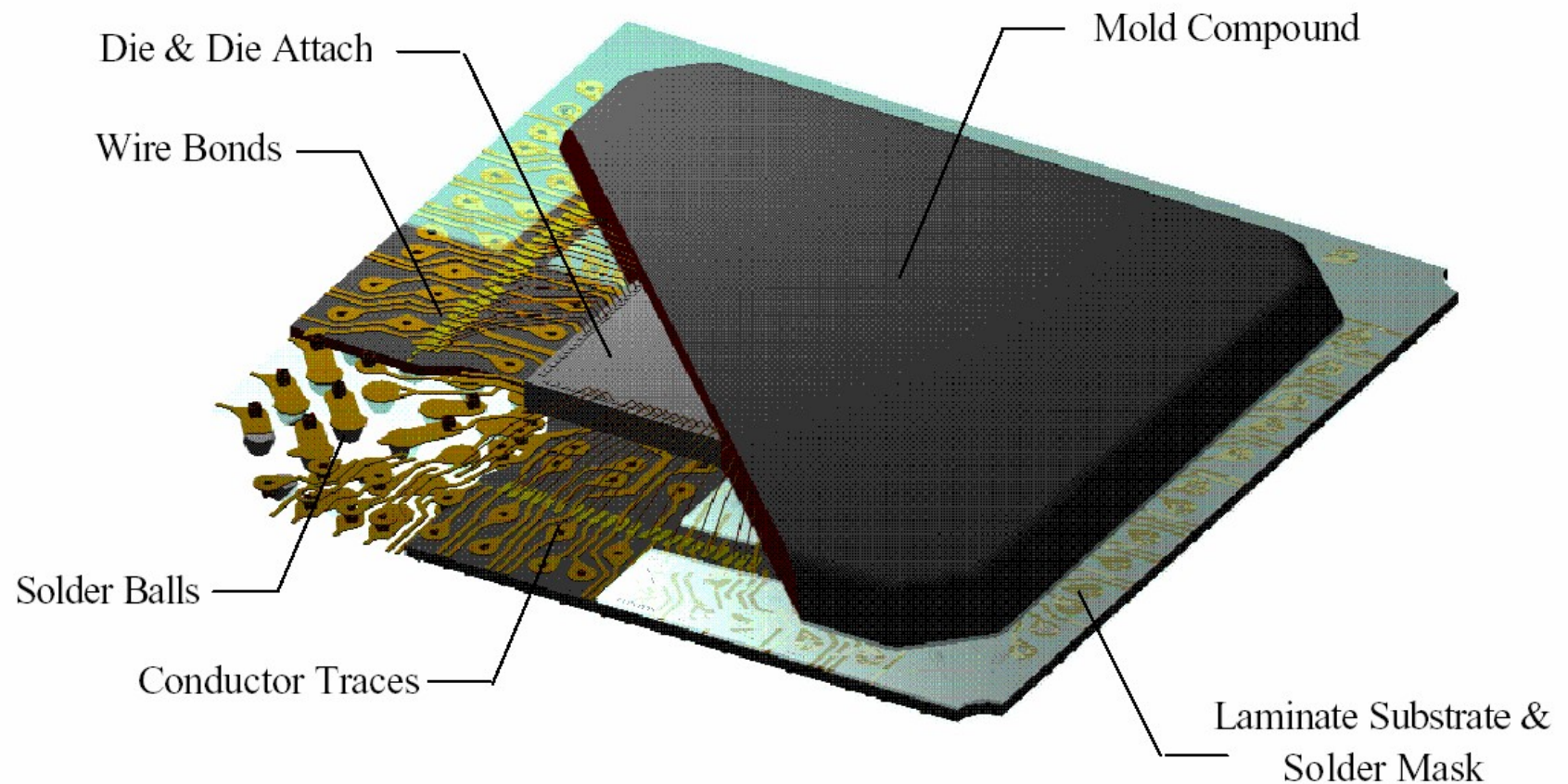


Ceramic chip

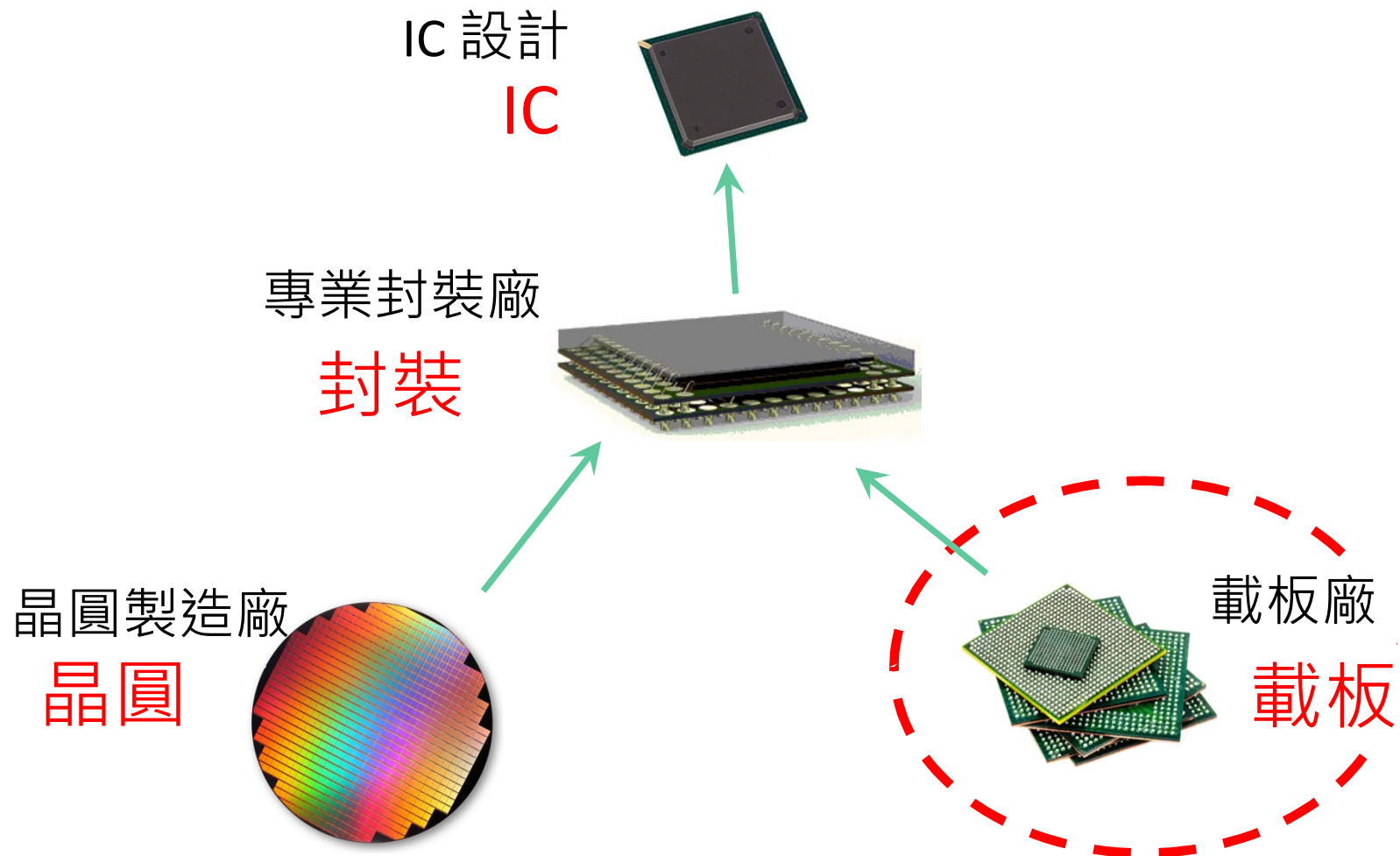
BGA Market size : 82 Billion units, 16 Billion US\$ in 2023



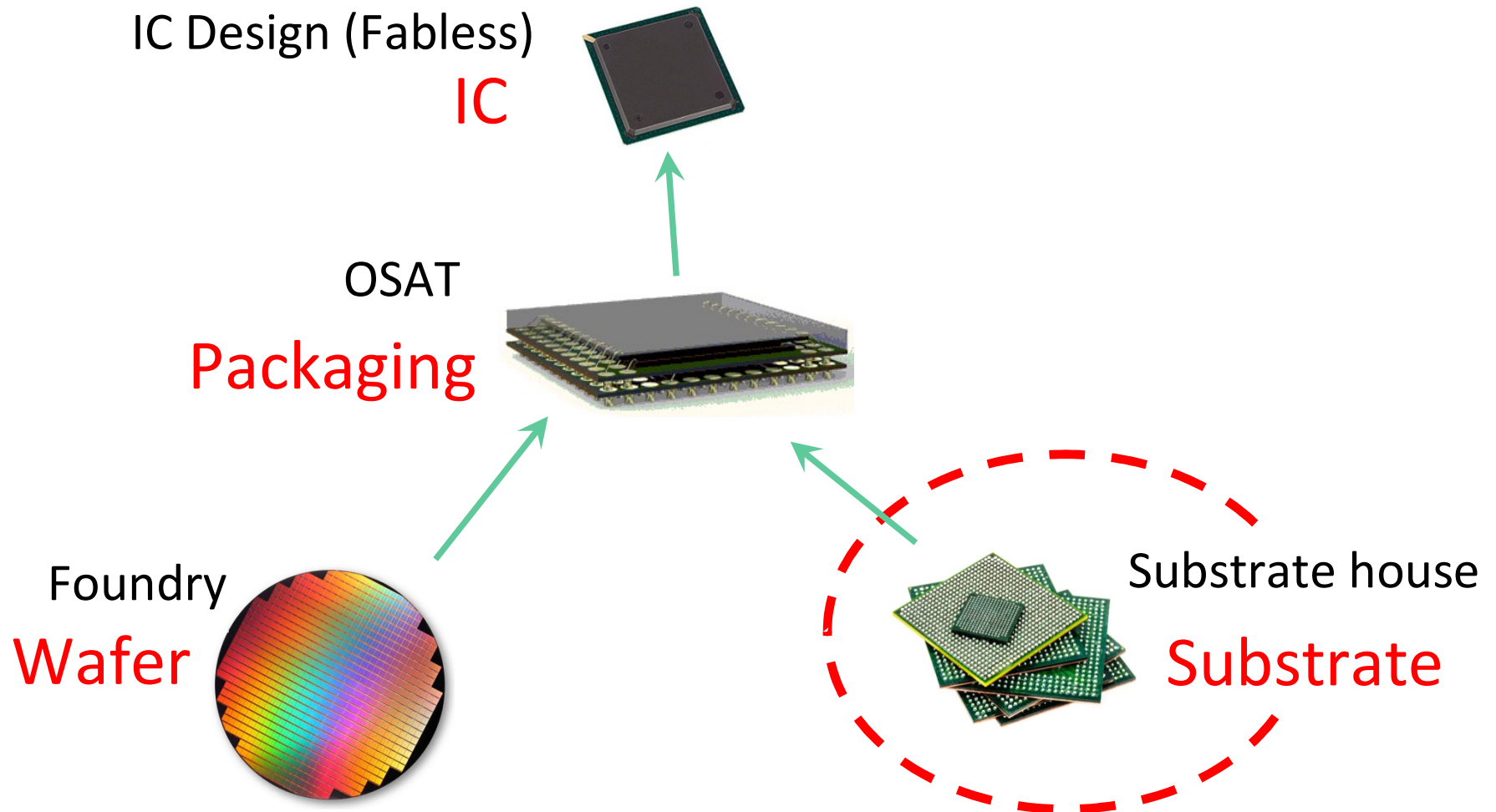
What Substrate Makers do?



IC 半導體上下游供應鏈關係



IC Manufacturing Supply Chain





About Kinsus

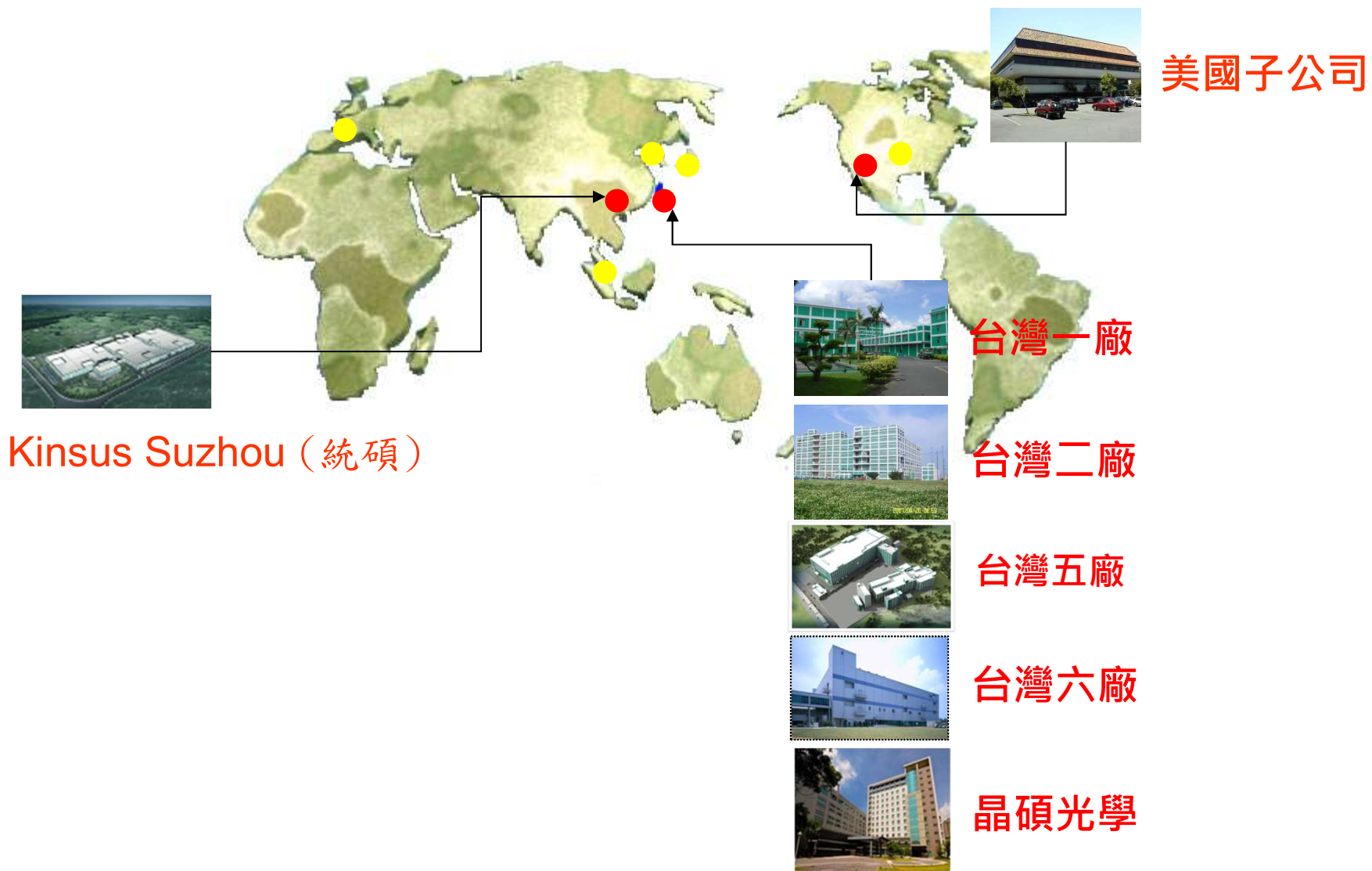
- 新屋 / 台灣
- 一廠 及 二廠
- 五廠 及 六廠
- Santa Clara / California
- 蘇州 / 中國
- 桃園 / 台灣

Basic Information

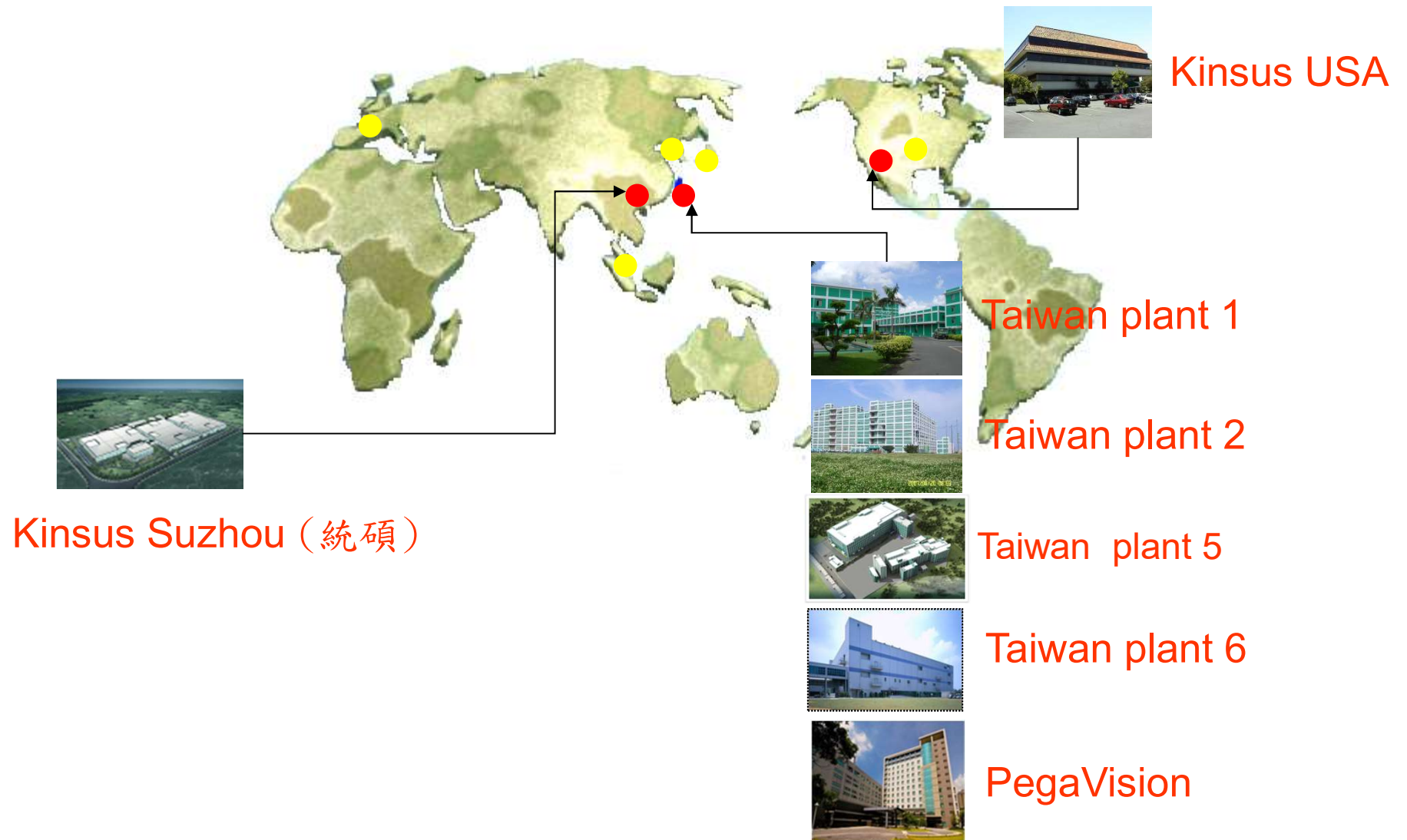


- Established in September 2000
IPO at TWSE in November 2004
- Capital : US\$ 147 Million (NT\$ 4.545 Billion)
- Campus :
 - Headquarters
 - Xin Wu / Taiwan
 - Plant 1 & 2
 - Plant 5 & 6
 - IC substrates
 - Kinsus USA
 - Santa Clara / California
 - Kinsus China
 - Suzhou / China
 - PegaVision
 - Taoyuan / Taiwan

位置

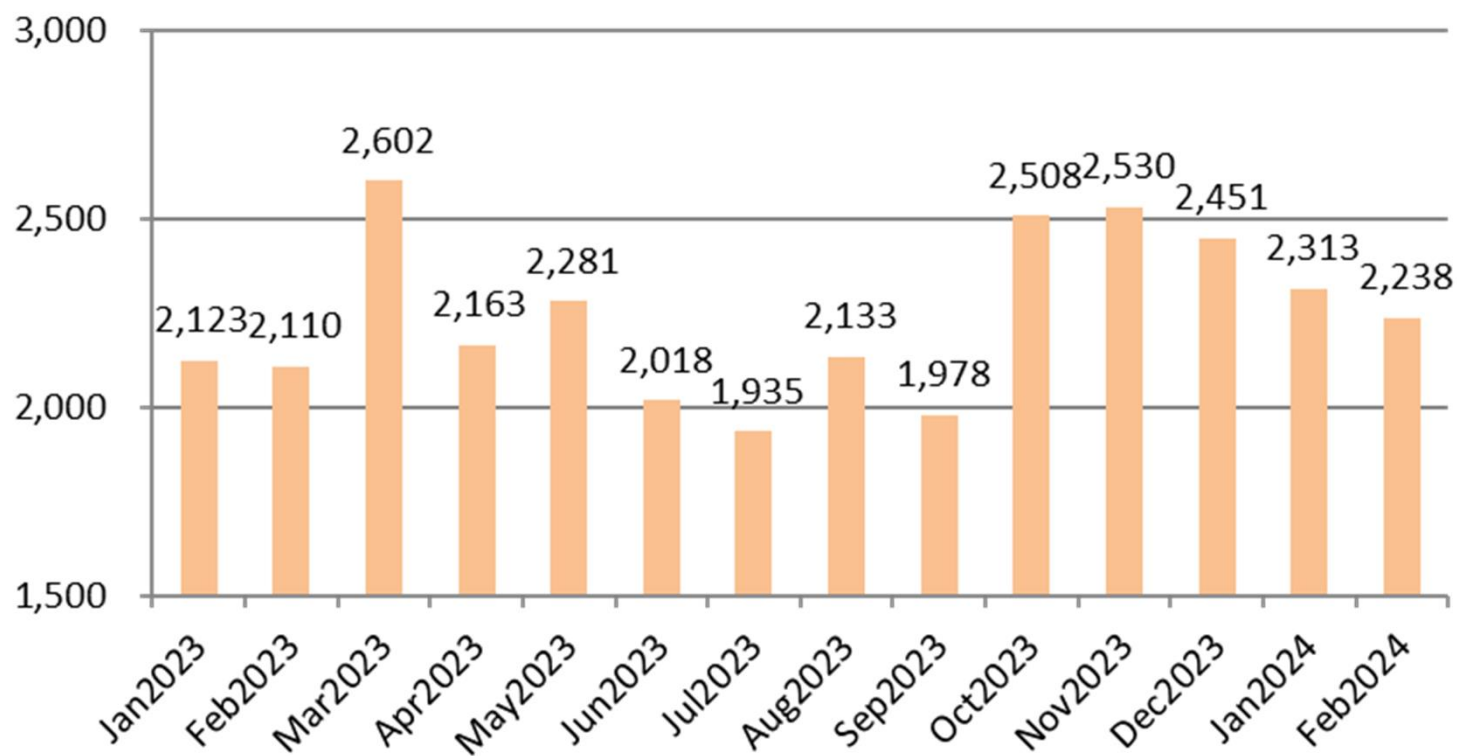


Locations

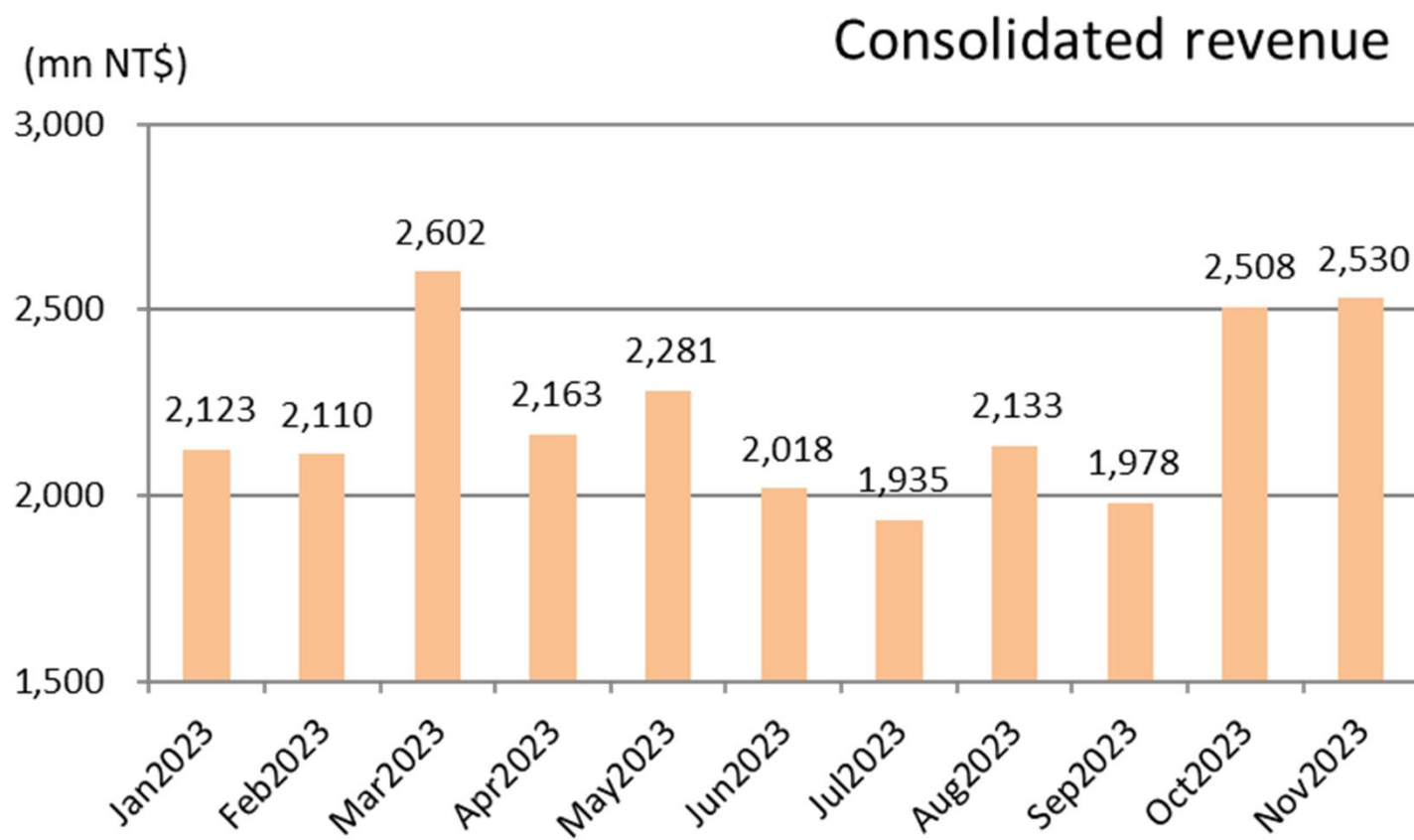


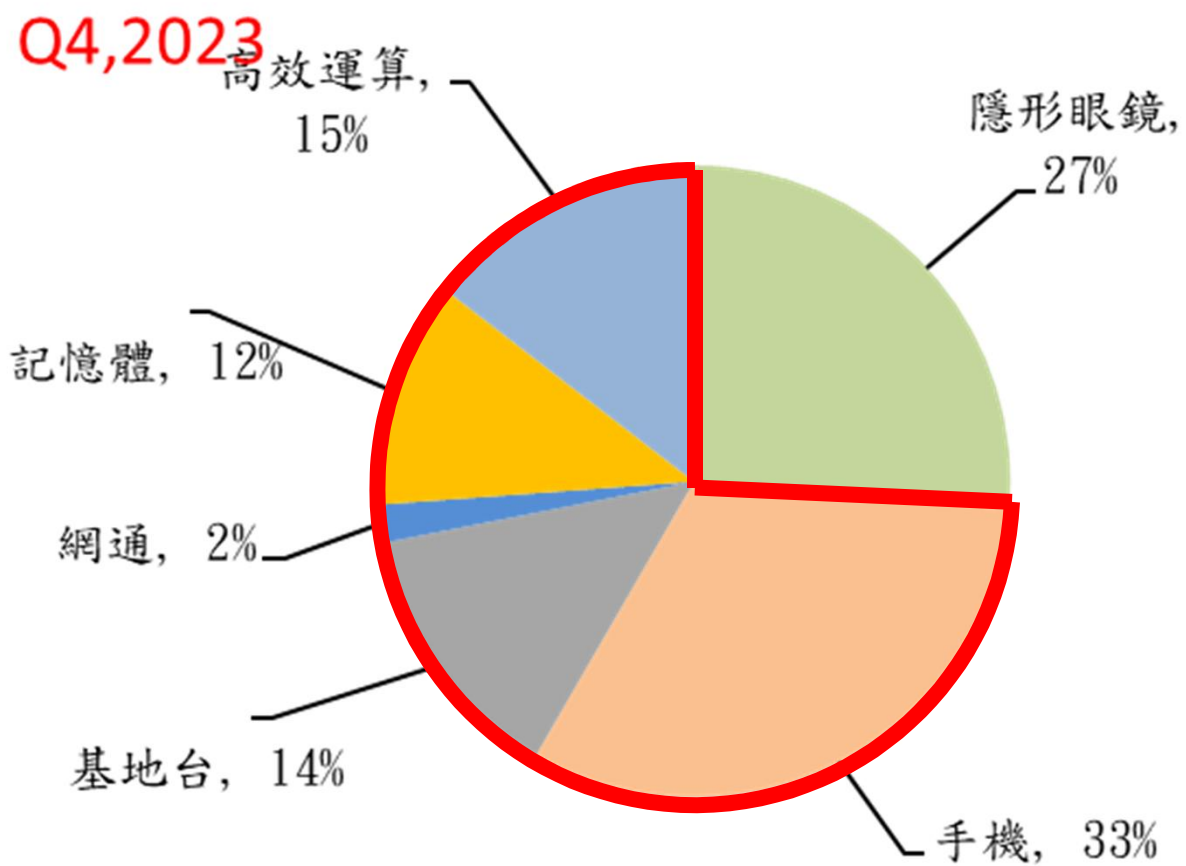
合併營收

(百萬元新台幣)



Monthly Revenue

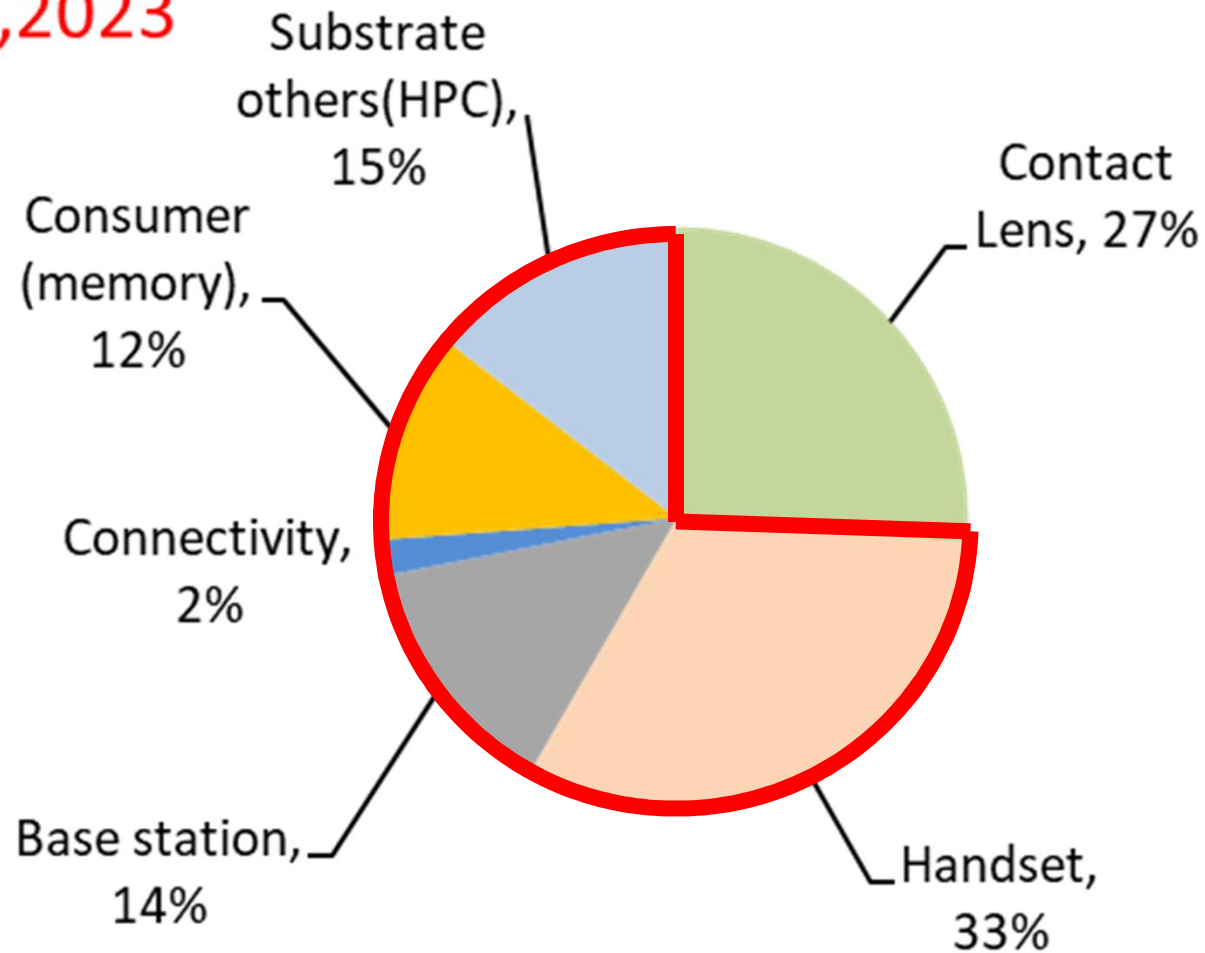




Product mix



Q4,2023





Thank you